

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Chung-Shi Liu</td><td>12/03/2008</td></tr><tr><td>Hsiang-Yi Wang</td><td>12/09/2008</td></tr><tr><td>Cheng-Tung Lin</td><td>12/09/2008</td></tr><tr><td>Chen-Hua Yu</td><td>12/09/2008</td></tr></tbody></table>	Name	Execution Date	Chung-Shi Liu	12/03/2008	Hsiang-Yi Wang	12/09/2008	Cheng-Tung Lin	12/09/2008	Chen-Hua Yu	12/09/2008	
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Hsiang-Yi Wang	12/09/2008										
Cheng-Tung Lin	12/09/2008										
Chen-Hua Yu	12/09/2008										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Road 6										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12354558</td></tr></tbody></table>	Property Type	Number	Application Number:	12354558							
Property Type	Number										
Application Number:	12354558										
CORRESPONDENCE DATA											
Fax Number:	(214)200-0853										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	214-651-5000										
Email:	ipdocketing@haynesboone.com										
Correspondent Name:	HAYNES AND BOONE, LLP										
Address Line 1:	2323 Victory Avenue										
Address Line 2:	Suite 700										
Address Line 4:	Dallas, TEXAS 75219										
ATTORNEY DOCKET NUMBER:	24061.1160										
NAME OF SUBMITTER:	Liem T. Do										
Total Attachments: 4											

CH 12354558 \$40.00

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PATENT  
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Docket No.: 2008-0373 / 24061.1160  
Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

- |     |                |    |   |
|-----|----------------|----|---|
| (1) | Chung-Shi Liu  | of | No. 10, Alley 41, Lane 139, Chia-Chiao Road<br>Shin-Chu, Taiwan, R. O.C.            |
| (2) | Hsiang-Yi Wang | of | Room B, 5F, No. 33, Jinshan 9th Street<br>Hsin-Chu City 300, Taiwan, R.O.C.         |
| (3) | Cheng-Tung Lin | of | 5F, No. 6, Alley 39, Lane 152, Sec. 2, Zhongxing Rd.<br>Hsinchu 300, Taiwan, R.O.C. |
| (4) | Chen-Hua Yu    | of | No. 3, 38 Waterfront Road 2<br>Hsin-Chu, Taiwan, R.O.C.                             |

have invented certain improvements in

### ADVANCED METAL GATE METHOD AND DEVICE

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
       filed on            and assigned application number           ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

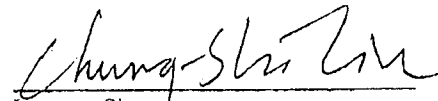
AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Chung-Shi Liu

Residence Address: No. 10, Alley 41, Lane 139, Chai-Chiao Road  
Shin-Chu, Taiwan, R. O.C.

Dated: 2008/12/13

  
Inventor Signature

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Inventor Name: Hsiang-Yi Wang

Residence Address: Room B, 5F, No. 33, Jinshan 9th Street  
Hsin-Chu City 300, Taiwan, R.O.C.

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

---

Inventor Name: Cheng-Tung Lin

Residence Address: 5F, No. 6, Alley 39, Lane 152, Sec. 2, Jhongsing Rd.  
Hsinchu 300, Taiwan, R.O.C.

Dated: \_\_\_\_\_

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Inventor Name: Chung-Shi Liu

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Shin-Chu, Taiwan, R. O.C.

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

Inventor Name: Hsiang-Yi Wang

Residence Address: Room B, 5F, No. 33, Jinshan 9th Street  
Hsin-Chu City 300, Taiwan, R.O.C.

Dated: 2008/12/09

Hsiang-Yi Wang  
\_\_\_\_\_  
Inventor Signature

Inventor Name: Cheng-Tung Lin

Residence Address: 5F, No. 6, Alley 39, Lane 152, Sec. 2, Jhongsing Rd.  
Hsinchu 300, Taiwan, R.O.C.

Dated: 2008/12/09

Cheng-Tung Lin  
\_\_\_\_\_  
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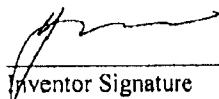
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Inventor Name: Chen-Hua Yu

Residence Address: No. 3, 38 Waterfront Road 2  
Hsin-Chu, Taiwan, R.O.C.

Dated: \_\_\_\_\_

12/09/08

  
Inventor Signature